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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

This application is a CON of 10/031,000 01/16/2002 PAT 6,780,668  
which is a 371 of PCT/JP00/04699 07/13/2000*CME*

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

*CME*JAPAN 11-202847 07/16/1999  
JAPAN 2000-63686 03/08/2000

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance		DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged <i>Chenard</i> Examiner's Signature	Initials	JAPAN	35	10	1

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## TITLE

Semiconductor device package manufacturing method and semiconductor device package manufactured by the method

<input type="checkbox"/> All Fees
<input type="checkbox"/> 1.16 Fees ( Filing )